Supplementary Information (SI) for Journal of Materials Chemistry C. This journal is © The Royal Society of Chemistry 2025

## **Supporting Information**

## Enargite (Cu<sub>3</sub>AsS<sub>4</sub>): A Ductile Mid-Temperature Thermoelectric Material

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Fig. S1 AMSET - Interpolation factor convergence test at fixed temperature and carrier concentration.

## S1.1. Cahill-Pohl and Slack model

Generally, the lattice thermal conductivity through Cahill and Slack model is manually estimated from elastic properties. The minimum lattice thermal conductivity is estimated by Cahill model<sup>1</sup> which is given by,

$$\kappa_{min} = \frac{k_B}{2.48} n^{2/3} (v_L + 2v_T) \tag{1}$$

The number density (n) is

$$n = \frac{Z}{V} \tag{2}$$

Where, Z - formula unit, V - volume of the unit cell  $(m^3)$ .

The longitudinal and transverse sound velocity is given as<sup>2</sup>

$$v_L = \left(\frac{B + \frac{4G}{3}}{\rho}\right)^{\frac{1}{2}} \tag{3}$$

$$v_T = \left(\frac{G}{\rho}\right)^{\frac{1}{2}} \tag{4}$$

Where, *B*, *G* are estimated from Voigt-Reuss-Hill approximation.

The mass density ( $\rho$ , unit is g/cm<sup>3</sup>) is

$$\rho = \frac{Z \times M.W}{N_A \times V} \tag{5}$$

Where, M.W – Molecular weight (g/mole),  $N_A$  – Avogadro number (6.022140 × 10<sup>23</sup> mole<sup>-1</sup>).

Further, the temperature dependent lattice thermal conductivity can be obtained from elastic constants through Slack model, expressed as,<sup>3-5</sup>

$$\kappa_L = A \frac{\bar{M} \,\theta_D^3 \delta}{\gamma^2 n^{2/3} T} \tag{6}$$

A – constant,

$$A = \frac{5.720 \times 10^7 \times 0.849}{2(1 - 0.514\gamma^{-1} + 0.228\gamma^{-2})}$$
(7)

The average atomic mass  $\overline{M}$  is

$$\overline{M} = \frac{M.W}{n} \tag{8}$$

The Debye temperature  $\theta_D$  is

$$\theta_D = \frac{h}{k_B} v_m \left(\frac{3N}{4\pi V}\right)^{1/3} \tag{9}$$

Here  $v_m$  is the average sound velocity, given by

$$v_m = \frac{1}{\left[ \left[ \frac{1}{3} \left( \frac{2}{v_T^3} + \frac{1}{v_L^3} \right) \right] \right]^{1/3}}$$

(10)

The average volume per atom  $\delta$  is

$$\delta = \left(\frac{V}{n}\right)^{1/3} \tag{11}$$

 ${\it N}$  - number of atoms in the formula unit

Grüneisen parameter, 
$$\gamma = \frac{3}{2} \left( \frac{1+v}{2-3v} \right)$$
 (12)

Poisson's ratio,
$$v = \frac{1 - 2\left(\frac{v_T}{v_L}\right)^2}{2 - 2\left(\frac{v_T}{v_L}\right)^2}$$

(13)



**Fig. S2 (a)** *q*-mesh Convergence test and **(b)** direction dependent lattice thermal conductivity against temperature for Cu<sub>3</sub>AsS<sub>4</sub> using Phono3py with non-analytical term correction and isotopic scattering.



Fig. S3 (a) Cutoff distance, (b) q-grid and (c) scaleboard convergence test. (d) Direction dependent lattice thermal conductivity against temperature for  $Cu_3AsS_4$  using ShengBTE.



S1.2. Transport properties of n-type Cu<sub>3</sub>AsS<sub>4</sub>

Fig. S4 (a) Relaxation time for electrons and (b) electrical conductivity for n-type Cu<sub>3</sub>AsS<sub>4</sub>



Fig. S5 (a) Seebeck coefficient and (b) power factor for n-type Cu<sub>3</sub>AsS<sub>4</sub>.

Transport Properties	<sup>Т</sup> (К)	p-type Cu <sub>3</sub> AsS <sub>4</sub>	n-type Cu <sub>3</sub> AsS <sub>4</sub>
τ <sub>tot</sub> (fs)	300	11.9	3.85
	600	5.05	1.63
	900	2.98	1.03
σ (S m <sup>-1</sup> )	300	5019.89	13040.05
	600	2261.33	3183.02
	900	1397.83	1101.11
S (μV K <sup>-1</sup> )	300	341	-243
	600	460	-334
	900	508	-398

**Table S1**. Temperature dependent total relaxation time  $({}^{\tau}_{tot})$ , electrical conductivity  $(\sigma)$  and Seebeck coefficient (*S*) for p- and n-type Cu<sub>3</sub>AsS<sub>4</sub> for the carrier concentration of 1×10<sup>19</sup> cm<sup>-3</sup>.

**Table S2**. Comparison of the optimum thermoelectric power factor (PF) and corresponding carrier concentration (*n*) for p- and n-type  $Cu_3AsS_4$  at 300 K, 600 K and 900 K.

Cu <sub>3</sub> AsS <sub>4</sub>	Т (К)	Optimum PF	п	
		(mW m <sup>-1</sup> K <sup>-2</sup> )	(cm <sup>-3</sup> )	
p-type	300	1.49	$3.5  imes 10^{20}$	
	600	1.90	$4.0  imes 10^{20}$	
	900	1.80	$5.0  imes 10^{20}$	
n-type	300	0.82	$1.8  imes 10^{19}$	
	600	0.51	$5.0 \times 10^{19}$	
	900	0.36	$1.1  imes 10^{20}$	



Fig. S6 Electronic thermal conductivity for n-type Cu<sub>3</sub>AsS<sub>4</sub>.



Fig. S7 Total thermal conductivity for p-type  $Cu_3AsS_4$  with  $\kappa_L$  obtained from (a) mDC, (b) Slack and (c) PBTE-RTA approaches.



Fig. S8 Total thermal conductivity for n-type  $Cu_3AsS_4$  with  $\kappa_L$  obtained from (a) mDC, (b) Slack, (c) PBTE-RTA, and (d) PBTE-Iterative approaches.

**Table S3**. Temperature dependent electronic thermal conductivity ( ${}^{\kappa_e}$ ) and total thermal conductivity ( ${}^{\kappa_{Total}}$ ) for p- and n-type Cu<sub>3</sub>AsS<sub>4</sub>. Four sets of  ${}^{\kappa_{Total}}$  values are presented: each calculated with lattice thermal conductivity ( ${}^{\kappa_L}$ ) obtained from the mDC, Slack, PBTE-RTA and PBTE-Iterative approaches. For better comparison, all the values are given for the carrier concentration of 1×10<sup>19</sup> cm<sup>-3</sup>.

Transport Properties	<sup>T</sup> (K)	p-type Cu <sub>3</sub> AsS <sub>4</sub>	n-type Cu <sub>3</sub> AsS <sub>4</sub>
	300	0.034	0.051
$(W m^{-1} K^{-1})$	600	0.024	0.018
	900	0.017	0.008
Kratal	300	1.207	1.224
$(\mathbf{W} \mathbf{m}^{-1} \mathbf{K}^{-1})$	600	0.535	0.529
( <sup>K</sup> <sup>L</sup> from mDC)	900	0.344	0.336
κ <sub>Total</sub>	300	1.058	1.075
$(W m^{-1} K^{-1})$	600	0.536	0.530
( <sup><i>nL</i></sup> from Slack)	900	0.358	0.349
κ <sub>Total</sub>	300	3.020	3.037
$(W m^{-1} K^{-1})$	600	1.471	1.465
( <sup>~L</sup> from PBTE-RTA)	900	0.976	0.967
κ <sub>Total</sub>	300	3.199	3.216
$(\mathbf{W} \mathbf{m}^{-1} \mathbf{K}^{-1})$	600	1.562	1.556
(" <sup>L</sup> trom PBTE-Iterative)	900	1.038	1.029



Fig. S9 The calculated zT for n-type Cu<sub>3</sub>AsS<sub>4</sub> with  $\kappa_L$  derived from (a) mDC, (b) Slack, (c) PBTE-RTA, and (d) PBTE-Iterative approaches.

**Table S4**. Optimum Figure of merit (*zT*) and corresponding carrier concentration (*n*) for p and n-type  $Cu_3AsS_4$  at different temperatures (300 K, 600 K and 900 K), computed using four different phonon transport approaches such as mDC, Slack, PBTE-RTA and PBTE-Iterative.

Approaches used to calculate <i>k<sub>L</sub></i>	T (K)	p-type		n-type	
		zT	<i>n</i> (cm <sup>-3</sup> )	zT	<i>n</i> (cm <sup>-3</sup> )
mDC	300	0.26	$1.9  imes 10^{20}$	0.20	$1.6 \times 10^{19}$
	600	1.19	$1.3  imes 10^{20}$	0.53	$4.0  imes 10^{19}$
	900	2.31	$1.4 \times 10^{20}$	0.83	$7.0  imes 10^{19}$
Slack	300	0.29	$1.8  imes 10^{20}$	0.22	$1.5 \times 10^{19}$
	600	1.19	$1.3  imes 10^{20}$	0.53	$4.0  imes 10^{19}$
	900	2.25	$1.4 \times 10^{20}$	0.80	$7.0  imes 10^{19}$
PBTE-RTA	300	0.12	$2.6 \times 10^{19}$	0.08	$1.6 \times 10^{19}$
	600	0.57	$2.2 \times 10^{19}$	0.20	$4.0  imes 10^{19}$
	900	1.12	$2.4 \times 10^{19}$	0.32	$9.0  imes 10^{19}$
PBTE- Iterative	300	0.12	$2.6 \times 10^{19}$	0.06	$4.0 \times 10^{19}$
	600	0.54	$2.2 \times 10^{20}$	0.19	$4.5 \times 10^{19}$
	900	1.07	$2.4 \times 10^{20}$	0.30	$9.0 \times 10^{19}$

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